

Title (en)  
METHOD FOR MAKING THIN FILMS IN METAL/CERAMIC COMPOSITE

Title (de)  
HERSTELLUNGSVERFAHREN FÜR DÜNNE BÄNDER AUS METALL/KERAMIK-KOMPOSITMATERIAL

Title (fr)  
PROCEDE DE FABRICATION DE FILMS MINCES EN COMPOSITE METAL/CERAMIQUE

Publication  
**EP 1343600 A1 20030917 (FR)**

Application  
**EP 01999450 A 20011206**

Priority  
• FR 0103855 W 20011206  
• FR 0015984 A 20001208

Abstract (en)  
[origin: WO0245888A1] The invention concerns a method for making thin films in metal/ceramic composite, characterised in that it consists in: a) preparing a suspension (S) in an organic solvent from a substantially homogeneous mixture of ceramic reinforcements of metal particles, a binder, a plasticizing agent and an organic dispersant, the metal particles constituting at least 5 wt. % of the suspension; b) tape casting the suspension (S) to form a thin film (B), then eliminating organic compounds contained in the binder and the plasticizing agent from said thin film; c) densifying the thin film from which said organic compounds have been removed in an oven.

IPC 1-7  
**B22F 3/22**

IPC 8 full level  
**B32B 37/06** (2006.01); **B22F 1/10** (2022.01); **B22F 3/22** (2006.01); **B22F 5/00** (2006.01); **B22F 7/04** (2006.01)

CPC (source: EP KR US)  
**B22F 1/10** (2022.01 - EP KR US); **B22F 3/22** (2013.01 - EP KR US); **B22F 5/006** (2013.01 - EP US); **B22F 2998/00** (2013.01 - EP US); **B22F 2998/10** (2013.01 - EP US)

C-Set (source: EP US)  
1. **B22F 2998/00 + B22F 7/02**  
2. **B22F 2998/10 + B22F 9/04 + B22F 3/22 + B22F 3/10**  
3. **B22F 2998/10 + B22F 9/04 + B22F 3/22 + B22F 3/18**

Citation (search report)  
See references of WO 0245888A1

Designated contracting state (EPC)  
AT DE FI FR GB IE

DOCDB simple family (publication)  
**WO 0245888 A1 20020613**; AT E360493 T1 20070515; AU 1618802 A 20020618; CN 1247352 C 20060329; CN 1479659 A 20040303; DE 60128133 D1 20070606; DE 60128133 T2 20071227; EP 1343600 A1 20030917; EP 1343600 B1 20070425; FR 2818015 A1 20020614; FR 2818015 B1 20030926; JP 2004515648 A 20040527; JP 4146228 B2 20080910; KR 100847129 B1 20080718; KR 20030069179 A 20030825; US 2004013556 A1 20040122; US 2009208645 A1 20090820; US 7585456 B2 20090908; US 7871562 B2 20110118

DOCDB simple family (application)  
**FR 0103855 W 20011206**; AT 01999450 T 20011206; AU 1618802 A 20011206; CN 01820133 A 20011206; DE 60128133 T 20011206; EP 01999450 A 20011206; FR 0015984 A 20001208; JP 2002547657 A 20011206; KR 20037007642 A 20030607; US 43341303 A 20030604; US 43499409 A 20090504